

FGF PLA Copper

FGF PLA COPPER is filled with 80% copper. With FGF PLA COPPER you can create the most beautiful objects with real METAL characteristics, such as a 3 x higher weight than PLA, a METAL feel & touch and thermal-conductivity. Due to the high percentage of fillers FGF PLA COPPER has virtually no shrinkage.

Material features:

- Approx. 80% copper content
- PLA-based, 3 times heavier
- Metal feel & “cold” touch
- Quick & easy polishing and other post-processing

Packaging:

FGF PLA Copper is available in 20kg bag

Processing recommendations

Drying	8hr, 50°C*. <250ppm
Zone 1 Temperature	160±20 °C
Zone 2 Temperature	180±20 °C
Zone 3 Temperature	175±20 °C
Mass temperature	184 °C
Die temperature	160±20 °C

Material properties

Description	Testmethod	Typical value
Specific gravity	ISO 1183	3,41 g/cc
MFR 210°C/2,16 kg	ISO 1133	85 g/10min
Tensile Strength at Yield	ISO 527	16 Mpa
Tensile Strength at Break	ISO 527	14 Mpa
Elongation-Strain at Yield	ISO 527	1,6%
Elongation-Strain at Break	ISO 527	31,3%
Tensile modulus	ISO 527	3550 Mpa
Impact strength - Charpy notched 23°C	ISO 179	2,9 kJ/m2
Vicat softening temperature	ISO 306 B50	N/A
Mold shrinkage	Internal method (ISO 294-4 based)	0,11%

Additional info:

Storage: Cool and dry (15-25°C) and away from UV light. This enhances the shelf life significantly.

* Please consider the use of a hardened steel nozzle when printing with MT-COPPER .

The copper powder inside makes the filament abrasive and will result in fast wear of regular brass nozzles.